

ABSTRACT

**Method and Device for a Forced
Wet-Chemical Treatment of Surfaces**

The invention relates to the wet-chemical treatment of surfaces of a material. Especially, the invention relates to an accelerated treatment of structures in printed circuit board technology. According to the inventive method, a puls-like spray jet of the treatment fluid is produced and directed against the surface of the material. This causes a pronounced impact action against the base of a structure to be processed so that the amount of treatment time which is necessary is substantially reduced. The pressure-free and accelerated outflow of the treatment fluid from the structure channels in the pauses between pulses results in the flanks of the structures or circuit-board conductors being subjected to less wet-chemical processing than in the prior art. In case of chemical etching the result is a smaller undercutting.